PRELIMINARY

VLA585-01R

DRIVER FOR IGBT MODULES



FEATURES

- -Low height, DIP structure
- -Isolated gate signal by pulse transformer
- -Corresponding to gate signal ON Duty 100%
- -Dual gate drive circuits
- -Built in isolated DC-DC converter for gate drive
- -Built in short circuit protection with soft gate shut down
- -Adjustable fall time on activity of short circuit protection
- -Output peak gate current is +/-20A(max)
- -Isolation voltage is 4000Vrms (for 1 minute)
- -CMOS compatible input interface (Input low active type)
- -Low voltage lock out for gate power supply(VCC)

TARGETED IGBT MODULES

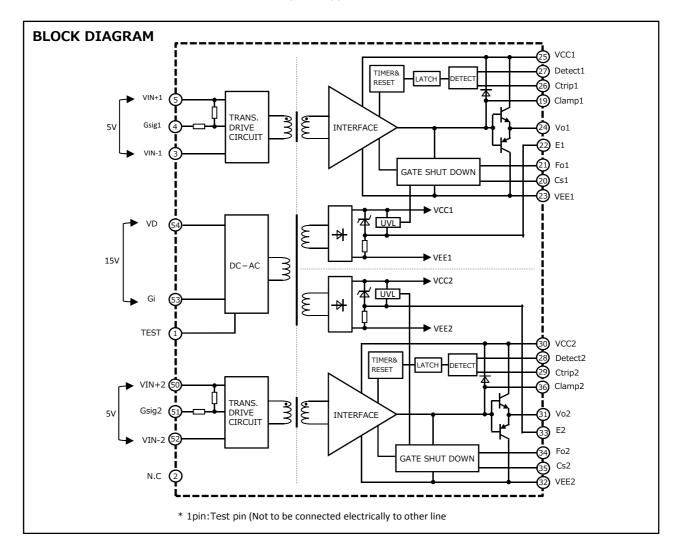
 $V_{CES} = 600V$ series up to 600A class

 $V_{CES} = 1200V$ series up to 1400A class

 $V_{CES} = 1700V$ series up to 1400A class

APPLICATIONS

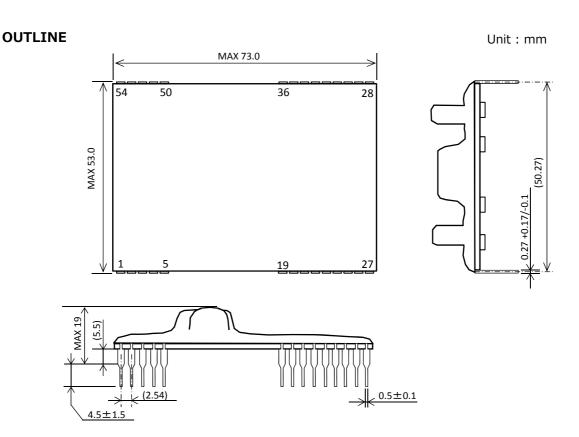
To drive IGBT modules for inverter or AC servo system application



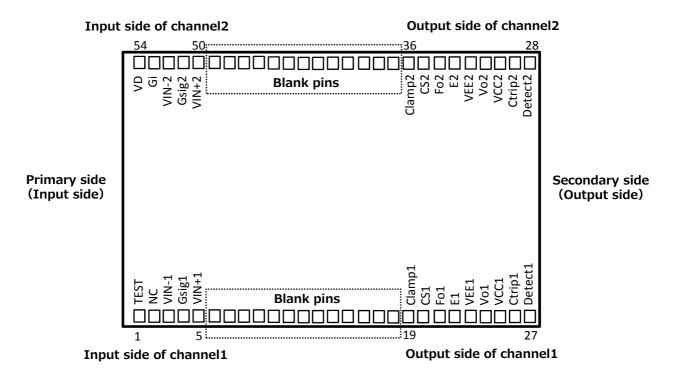
PRELIMINARY

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PIN ASSIGNMENT



DIP-GAM

PRELIMINARY

VLA585-01R

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MAXIMUM RATINGS (Unless otherwise noted, Ta=25 ℃)

		-		
Symbol	Item	Conditions	Ratings	Unit
VD	Supply voltage	Between VD and Gi	16.5	V
VIN	Supply voltage for gate signal	Between VIN+ and VIN-	6	V
V_Gsig	Gate signal voltage	Between Gsig and VIN-	6	V
IOHP	O. t	D 1 111 2	-20	Α
IOLP	Output peak current	Pulse width 3us	20	Α
Viso1	Isolation voltage between primary and secondary	Sine wave voltage, 60Hz, 1minute	4000	Vrms
Viso2	Isolation voltage between each output	Sine wave voltage, 60Hz, 1minute	4000	Vrms
Tc	Case temperature	Surface temperature of the exterior resin	100	$^{\circ}$
Topr	Operating temperature	No condensation allowable	-25 ~ 85	$^{\circ}$
Tstg	Storage temperature	No condensation allowable	-40 ~ 90	$^{\circ}$
IFo	Fault output current	Applied Fo pin	20	mA
VR_Det	Input voltage at Detect pin	Applied Detect pin	80	V
Idrive	Gate drive current	Gate average current (Total of 2 drive circuits) *Keep case temperature less than 100 ℃	200	mA

ELECTRICAL CHARACTERISTICS (Unless otherwise noted, Ta=25°C,VD=15V,VIN=5V,RG=1.5Ω)

Symbol	Item	Conditions	Limits			Unit
			Min	Тур	Max	Offic
VD	Supply voltage	Recommended range	14.5	15	15.5	V
VIN	Supply voltage for gate signal	Recommended range	4.75	5	5.25	٧
V_Gsig	Gate signal voltage	Recommended range	4.75	-	VIN	V
f	Switching frequency	Recommended range Keep total gate average current less than 200mA	-	-	50	kHz
RG	Gate resistance	Recommended range	0.5	-	-	Ω
VCC	VCC voltage	-	-	16.4	-	V
VEE	VEE voltage	-	-	-9	-	V
η	Gate supply efficiency	2 circuits total load current between VCC and VEE is 200mA	62	70	ı	%
VOH	"H" output voltage	Input "L" (Low active)	13.5	15.2	16.5	V
VOL	"L" output voltage	Input "H" (Low active)	-6	-8	-11	٧
tPLH	"L-H" propagation time	RG=1.5Ω, f=10kHz, C_load:0.33uF	-	0.36	-	us
tr	"L-H" rise time	RG=1.5Ω, f=10kHz, C_load:0.33uF	-	0.52	0.65	us
tPHL	"H-L" propagation time	RG=1.5Ω, f=10kHz, C_load:0.33uF	-	0.3	-	us
tf	"H-L" fall time	RG=1.5Ω, f=10kHz, C_load:0.33uF	-	0.12	0.25	us
ttimer	Timer	Between start and cancel of protection (Under input signal is off state)	1	-	2	ms
IFo	Fault output current	Applied Fo pin, Pull up resistance 4.7kΩ	-	5	-	mA
ttrip1	Masked time detect short circuit1	Detect pin:over than15V, Ctrip pin:open	-	3	-	us
ttrip2	Masked time detect short circuit2 *1	Detect pin:over than15V, Between Ctrip and E pin:capacitor 47pF	-	3.8	-	us
VSC	SC detect voltage	Collector voltage of IGBT	15	-	-	V
UVLO+_VCC	Under voltage lock out (Operation start)	VCC voltage	ı	12.6	ı	V
UVLOVCC	Under voltage lock out (Operation stop)	VCC voltage	-	11.7	-	V

^{*1} Length of wiring of capacitor masked time detect short-circuit is within 5cm from E and Ctrip pins coming and going

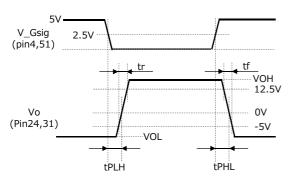
PRELIMINARY

VLA585-01R

DRIVER FOR IGBT MODULES

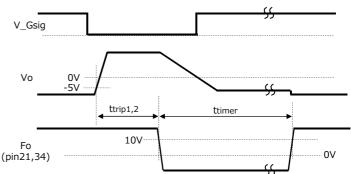
DEFFINITION OF CHARACTERISTICS

SWITCHING OPERATION

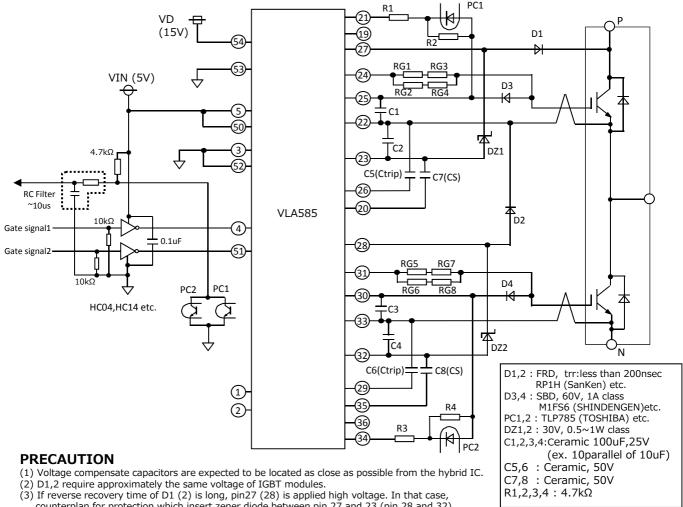


*RG= 1.5Ω , C_load:0.33uF, f=10kHz, ON Duty=50%

OPERATION OF SHORT CIRCUIT PROTECTION



APPLICATION EXAMPLE



- counterplan for protection which insert zener diode between pin 27 and 23 (pin 28 and 32) is necessary like above diagram.
- (4) In case pin 26 or 29 are operating, the Ctrip is expected to be wired as close as possible from pin. (Less than 5cm coming and going) In case of not using, please keep pin 26 or 29 open.

 (5) Minimize the area of closed circuit of gate circuit and input gate signal circuit so as not to be affected by induction noise.
- (6) When the built in short-circuit protection circuit need not be used, please connect resistance of 4.7k(1/4W) between pin 27 and 22 (pin 28 and 33). At that time, D1 (D2) and Dz1 (DZ2) are not require, and pin 21 and 34 are not necessary to be connected.
- (7) Pin1 is Test pin. Please not to be connected electrically to other line.
- (8) Please keep pin19 and 36 open ordinarily. These pins are exclusive to our specific product.
- (9) Please keep total gate average current less than maximum rating.
- (10) About the IC which drives gate signal on input side, it is not recommended to use the one whose output is open collector or open drain type



VLA585-01R

DRIVER FOR IGBT MODULES

OPERATION OF PROTECTION CIRCUIT

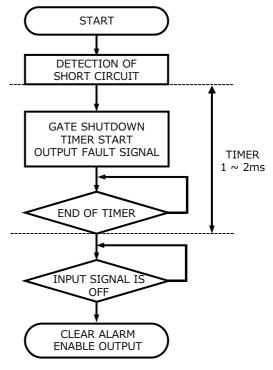
- (1) In case the gate voltage is "H" and the collector voltage is high, this hybrid IC will recognize the circuit as short circuit and immediately reduce the gate voltage. Besides, put out error signal ("L") which inform that protection circuit is operating at the same time from pin 21 or 34.
- (2) The protection circuit reset and resort to ordinary condition if input signal is "OFF" when the premised 1~2msec
- passed. ("OFF" period needs 10us or more)
 (3) When the output rises, the masked time detect short circuit (ttrip) is set up so that on-time of IGBT can be secured properly.
 - It is possible to adjust that time by connecting the capacitor (Ctrip) between pin26 and 22 (29 and 33).
- (4) When the short circuit protection works, the soft gate shut down circuit works to suppress collector surge voltage of IGBT. Furthermore, when it is necessary to be more soft, by adding a capacitor between Cs and VEE terminals, it is possible to make gate shut down speed more slow.

LATCH & TIMER RESET SYSTEM IN SHORT-CIRCUIT PROTECTION CIRCUIT

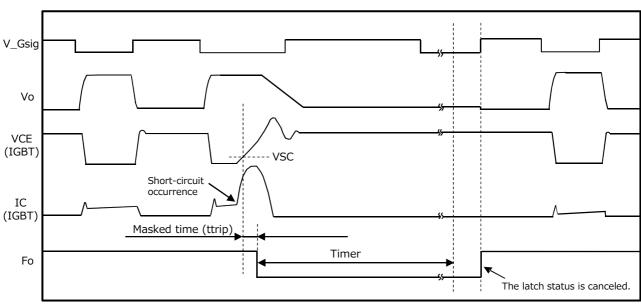
Once the short-circuit protection circuit starts, it shuts down the gate output and keeps alarm output, causing the latch status. This status is canceled if the input signal is OFF when specific time elapses after the activation of the short-circuit protection circuit. Then, gate output depending on input signals becomes possible. If the input signal is ON when specific time elapses, the latch status is not canceled: it is canceled when the signal becomes OFF.

As mentioned above, on the latch & timer reset system, the latch status is resulted after activation of the protection circuit and shutdown of the gate output. Therefore, during this period, gate output is not made no matter how much input signals are received. For this reason, it is possible to safely stop the entire equipment by sending error signals to the microcomputer during this period to stop all gate signals.

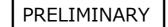
OPERATION FLOW ON DETECTING SHORT CIRCUIT



TIMING CHART







VLA585-01R

DRIVER FOR IGBT MODULES

FOR SAFETY USING

Great detail and careful attention are given to the production activity of Hics, such as the development, the quality of production, and in it's reliability. However the reliability of Hics depends not only on their own factors but also in their condition of usage. When handling Hics, please note the following cautions.

CAUTIONS			
Packing	The materials used in packing Hics can only withstand normal external conditions. When exposed to outside shocks, rain and certain environmental contaminators, the packing materials will deteriorates. Please take care in handling.		
Carrying	 Don't stack boxes too high. Avoid placing heavy materials on boxes. Boxes must be positioned correctly during transportation to avoid breakage. Don't throw or drop boxes. Keep boxes dry. Avoid rain or snow. Minimal vibration and shock during transportation is desirable. 		
Storage	 When storing Hics, please observe the following notices or possible deterioration of their electrical characteristics, risk of solder ability, and external damage may occur. 1) Devices must be stored where fluctuation of temperature and humidity is minimal, and must not be exposed to direct sunlight. Store at the normal temperature of 5 to 30 degrees Celsius with humidity at 40 to 60%. 2) Avoid locations where corrosive gasses are generated or where much dust accumulates. 3) Storage cases must be static proof. 4) Avoid putting weight on boxes. 		
Extended storage	When extended storage is necessary, Hics must be kept non-processed. When using Hics which have been stored for more than one year or under severe conditions, be sure to check that the exterior is free from flaw and other damages.		
Maximum ratings	To prevent any electrical damages, use Hics within the maximum ratings. The temperature, current, voltage, etc. must not exceed these conditions.		
Polarity	To protect Hics from destruction and deterioration due to wrong insertion, make sure of polarity in inserting leads into the board holes, conforming to the external view for the terminal arrangement.		

DIP-GAM

PRELIMINARY

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DRIVER FOR IGBT MODULES

Keep safety first in your circuit designs!

·ISAHAYA Electronics Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (1) placement of substitutive, auxiliary circuits, (2) use of non-flammable material or (3) prevention against any malfunction or mishap.

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